

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Byung Joon Han	03/24/2008
Nathapong Suthiwongsunthorn	03/03/2008
Pandi Chelvam Marimuthu	03/10/2008
Kock Liang Heng	03/03/2008
RECEIVING PARTY DATA	
Name:	STATS ChipPAC, Ltd.
Street Address:	10 Ang Mo Kio Street 65
Internal Address:	#05-17/20 Techpoint
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	569059
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12055171
CORRESPONDENCE DATA	
Fax Number:	(602)229-5690
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	602-229-5290
Email:	moneill@quarles.com
Correspondent Name:	Robert D. Atkins
Address Line 1:	QUARLES & BRADY LLP
Address Line 2:	TWO NORTH CENTRAL AVENUE
Address Line 4:	PHOENIX, ARIZONA 85004-2391
ATTORNEY DOCKET NUMBER:	125155.00088
NAME OF SUBMITTER:	Robert D. Atkins

CH \$40.00 12055171

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PATENT
REEL: 020699 FRAME: 0991

Total Attachments: 4

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PATENT

REEL: 020699 FRAME: 0992

ASSIGNMENT AND AGREEMENT

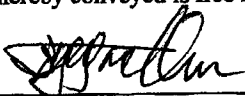
For good and valuable consideration, the receipt of which is hereby acknowledged, I, BYUNG JOON HAN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled WAFER INTEGRATED WITH PERMANENT CARRIER AND METHOD THEREFOR, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00088, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.


Signature for BYUNG JOON HAN


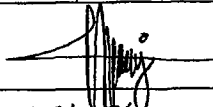
24 Mar. 2008

Witnessed on this date:

Signature of Witness:

Printed Name of Witness:

Address of Witness:


March 24, 2008

GUENI OMARANDAKI
776 # 02-58 WOODLANDS
CRESCENT SINGAPORE 730776

QBACTIVE\6095390.1

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, NATHAPONG SUTHIWONGSUNTHORN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled WAFER INTEGRATED WITH PERMANENT CARRIER AND METHOD THEREFOR, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00088, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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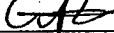
I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

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313108
Signature for NATHAPONG SUTHIWONGSUNTHORN

Witnessed on this date: 313108

Signature of Witness: 

Printed Name of Witness: Ge Pei, Patrick

Address of Witness: BLK 529, Woodlands Drive 14
#10-527, Singapore 730529

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ASSIGNMENT AND AGREEMENT

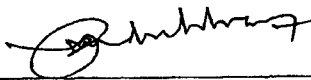
For good and valuable consideration, the receipt of which is hereby acknowledged, I, PANDI CHELVAM MARIMUTHU of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled WAFER INTEGRATED WITH PERMANENT CARRIER AND METHOD THEREFOR, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00088, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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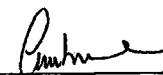
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March 10, 2008

Signature for PANDI CHELVAM MARIMUTHU

Witnessed on this date: March 10, 2008

Signature of Witness: 

Printed Name of Witness: CONSTANCE KOK

Address of Witness: BLK 23, #12-24, TELOK BLANGAH
CRESCENT, (090023)

QBACTIVE\6095393.1

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, KOCK LIANG HENG of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled WAFER INTEGRATED WITH PERMANENT CARRIER AND METHOD THEREFOR, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00088, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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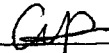


Signature for KOCK LIANG HENG

Witnessed on this date:

3/3/2008

Signature of Witness:



Printed Name of Witness:

Ge Pei, Patrick

Address of Witness:

BLK 529, Woodlands Drive 14

#10-527, Singapore 730529

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